

IN THE SPECIFICATION:

Pursuant to 37 C.F.R. § 1.121(b)(2)(ii), please delete the title of the invention and replace the same with the text enclosed in clean form hereinbelow. Also attached is a marked-up version of the title, as amended herein, in accordance with 37 C.F.R. § 1.121(b)(2)(iii).

**--STEREOLITHOGRAPHIC METHOD FOR FABRICATING STABILIZERS
FOR FLIP-CHIP TYPE SEMICONDUCTOR DEVICES--**

Pursuant to 37 C.F.R. § 1.121(b)(1)(ii), please replace paragraph [0009] of the above-referenced application with the following amended paragraph. A version with markings to show changes made is attached hereto in accordance with 37 C.F.R. § 1.121(b)(1)(iii).

C1 [0009] As noted previously and illustrated in FIG. 3, bond pads 202 are arranged on active solder bumps 220 secured to bond pads 202. Alternatively, the conductive structures may be any other known type of conductive structure, suitably configured as balls, bumps, or pillars. The conductive structures can be formed from any type of conductive material or combination of materials known to be useful as a conductive structure of a semiconductor device, including, without limitation, solders, other metals, metal alloys, conductive epoxies, conductor filled epoxies, and z-axis conductive elements.